MCP14A0303/4/5

3A Dual MOSFET Driver with Low Threshold Input and Enable

Features

- High-Peak Output Current: 3A (typical)
- Wide Input Supply Voltage Operating Range:
  - 4.5 to 18V
- Low Shoot-Through/Cross-Conduction Current in Output Stage
- High Capacitive Load Drive Capability:
  - 1800 pF in 12 ns (typical)
- Short Delay Times: 17 ns (t_{D1}), 21 ns (t_{D2}) (typical)
- Low Supply Current: 620 µA (typical)
- Low-Voltage Threshold Input and Enable with Hysteresis
- Latch-Up Protected: Withstands 500 mA Reverse Current
- Space-Saving Packages:
  - 8-Lead MSOP
  - 8-Lead SOIC
  - 8-Lead 2 x 3 TDFN

Applications

- Switch Mode Power Supplies
- Pulse Transformer Drive
- Line Drivers
- Level Translator
- Motor and Solenoid Drive

General Description

The MCP14A0303/4/5 devices are high-speed dual MOSFET drivers that are capable of providing up to 3A of peak current while operating from a single 4.5V to 18V supply. There are three output configurations available: dual inverting (MCP14A0303), dual noninverting (MCP14A0304) and complementary (MCP14A0305). These devices feature low shoot-through current, matched rise and fall times, and short propagation delays, which make them ideal for high switching frequency applications.

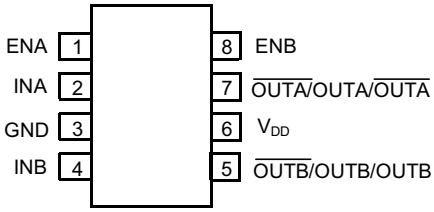
The MCP14A0303/4/5 family of devices offers enhanced control with enable functionality. The active-high Enable pins can be driven low to drive the corresponding outputs of the MCP14A0303/4/5 low, regardless of the status of the input pins. Integrated pull-up resistors allow the user to leave the Enable pins floating for standard operation.

These devices are highly latch-up resistant under any condition within their power and voltage ratings. They can accept up to 500 mA of reverse current being forced back into their outputs without damage or logic upset. All terminals are fully protected against electrostatic discharge (ESD) up to 2 kV (HBM) and 200V (MM).

Package Types

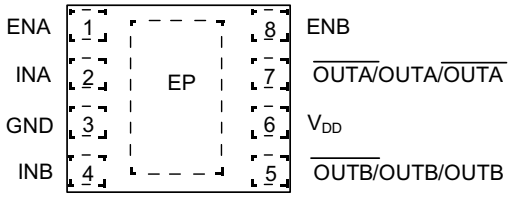
MCP14A0303/4/5

8-pin MSOP/SOIC



MCP14A0303/4/5

2 x 3 TDFN*



* Includes Exposed Thermal Pad (EP); see Table 3-1.

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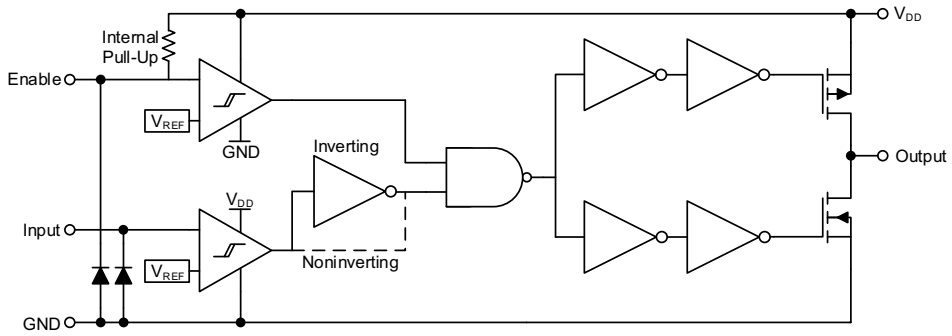
Functional Block Diagram



MCP14A0303: Dual Inverting

MCP14A0304: Dual Noninverting

MCP14A0305: Complementary: One Inverting, One Noninverting

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1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V_{DD}, Supply Voltage.....+20V

V_{IN}, Input Voltage.....(V_{DD} + 0.3V) to (GND – 0.3V)

V_{EN}, Enable Voltage.....(V_{DD} + 0.3V) to (GND – 0.3V)

Package Power Dissipation (T_A = +50°C)

8L MSOP 0.63W

8L SOIC 1.00W

8L 2 x 3 TDFN.....1.85W

ESD Protection on all pins .....2 kV (HBM)

ESD Protection on all pins .....200V (MM)

† **Notice:** Stresses above those listed under “Maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, T_A = +25°C, with 4.5V ≤ V_{DD} ≤ 18V.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Input						
Input Voltage Range	V_{IN}	GND – 0.3V	—	V_{DD} + 0.3	V	
Logic '1' High Input Voltage	V_{IH}	2.0	1.6	—	V	
Logic '0' Low Input Voltage	V_{IL}	—	1.3	0.8	V	
Input Voltage Hysteresis	$V_{HYST(IN)}$	—	0.3	—	V	
Input Current	I_{IN}	–1	—	+1	µA	0V ≤ V_{IN} ≤ V_{DD}
Enable						
Enable Voltage Range	V_{EN}	GND – 0.3V	—	V_{DD} + 0.3	V	
Logic '1' High Enable Voltage	V_{EH}	2.0	1.6	—	V	
Logic '0' Low Enable Voltage	V_{EL}	—	1.3	0.8	V	
Enable Voltage Hysteresis	$V_{HYST(EN)}$	—	0.3	—	V	
Enable Pin Pull-Up Resistance	R_{ENBL}	—	1.8	—	MΩ	V_{DD} = 18V, ENB = A_{GND}
Enable Input Current	I_{EN}	—	12	—	µA	V_{DD} = 18V, ENB = A_{GND}
Propagation Delay	t_{D3}	—	17	23	ns	V_{DD} = 18V, V_{EN} = 5V, see Figure 4-3 (**Note 1**)
Propagation Delay	t_{D4}	—	21	26	ns	V_{DD} = 18V, V_{EN} = 5V, see Figure 4-3 (**Note 1**)
Output						
High Output Voltage	V_{OH}	V_{DD} – 0.025	—	—	V	I_{OUT} = 0A
Low Output Voltage	V_{OL}	—	—	0.025	V	I_{OUT} = 0A
Output Resistance, High	R_{OH}	—	2.4	4	Ω	I_{OUT} = 10 mA, V_{DD} = 18V
Output Resistance, Low	R_{OL}	—	1.6	3	Ω	I_{OUT} = 10 mA, V_{DD} = 18V
Peak Output Current	I_{PK}	—	3	—	A	V_{DD} = 18V **(Note 1)**
Latch-Up Protection Withstand Reverse Current	I_{REV}	0.5	—	—	A	Duty cycle ≤ 2%, t ≤ 300 µs (**Note 1**)
Switching Time (Note 1)						
Rise Time	t_R	—	12	17	ns	V_{DD} = 18V, C_L = 1800 pF, see Figure 4-1, Figure 4-2
Fall Time	t_F	—	12	17	ns	V_{DD} = 18V, C_L = 1800 pF, see Figure 4-1, Figure 4-2
Delay Time	t_{D1}	—	17	23	ns	V_{DD} = 18V, V_{IN} = 5V, see Figure 4-1, Figure 4-2
	t_{D2}	—	21	26	ns	V_{DD} = 18V, V_{IN} = 5V, see Figure 4-1, Figure 4-2
Power Supply						
Supply Voltage	V_{DD}	4.5	—	18	V	
Power Supply Current	I_{DD}	—	620	900	µA	$V_{INA/B}$ = 3V, $V_{ENA/B}$ = 3V
	I_{DD}	—	620	900	µA	$V_{INA/B}$ = 0V, $V_{ENA/B}$ = 3V
	I_{DD}	—	620	900	µA	$V_{INA/B}$ = 3V, $V_{ENA/B}$ = 0V
	I_{DD}	—	620	900	µA	$V_{INA/B}$ = 0V, $V_{ENA/B}$ = 0V

Note 1: Tested during characterization, not production tested.

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DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

Electrical Specifications: Unless otherwise indicated, over the operating range with 4.5V ≤ V_{DD} ≤ 18V.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Input						
Input Voltage Range	V_{IN}	GND – 0.3V	—	V_{DD} + 0.3	V	
Logic '1' High Input Voltage	V_{IH}	2.0	1.6	—	V	
Logic '0' Low Input Voltage	V_{IL}	—	1.3	0.8	V	
Input Voltage Hysteresis	$V_{HYST(IN)}$	—	0.3	—	V	
Input Current	I_{IN}	–10	—	+10	µA	0V ≤ V_{IN} ≤ V_{DD}
Enable						
Enable Voltage Range	V_{EN}	GND – 0.3V	—	V_{DD} + 0.3	V	
Logic '1' High Enable Voltage	V_{EH}	2.0	1.6	—	V	
Logic '0' Low Enable Voltage	V_{EL}	—	1.3	0.8	V	
Enable Voltage Hysteresis	$V_{HYST(EN)}$	—	0.3	—	V	
Enable Input Current	I_{EN}	—	12	—	µA	V_{DD} = 18V, ENB = A_{GND}
Propagation Delay	t_{D3}	—	21	27	ns	V_{DD} = 18V, V_{EN} = 5V, T_A = +125°C, see Figure 4-3 (**Note 1**)
Propagation Delay	t_{D4}	—	25	31	ns	V_{DD} = 18V, V_{EN} = 5V, T_A = +125°C, see Figure 4-3 (**Note 1**)
Output						
High Output Voltage	V_{OH}	V_{DD} – 0.025	—	—	V	DC Test
Low Output Voltage	V_{OL}	—	—	0.025	V	DC Test
Output Resistance, High	R_{OH}	—	—	5	Ω	I_{OUT} = 10 mA, V_{DD} = 18V
Output Resistance, Low	R_{OL}	—	—	4	Ω	I_{OUT} = 10 mA, V_{DD} = 18V

Note 1: Tested during characterization, not production tested.

DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

Electrical Specifications: Unless otherwise indicated, over the operating range with 4.5V ≤ V_{DD} ≤ 18V.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Switching Time (Note 1)						
Rise Time	t_R	—	14	19	ns	V_{DD} = 18V, C_L = 1800 pF, T_A = +125°C, see Figure 4-1, Figure 4-2
Fall Time	t_F	—	14	19	ns	V_{DD} = 18V, C_L = 1800 pF, T_A = +125°C, see Figure 4-1, Figure 4-2
Delay Time	t_{D1}	—	21	27	ns	V_{DD} = 18V, V_{IN} = 5V, T_A = +125°C, see Figure 4-1, Figure 4-2
	t_{D2}	—	25	31	ns	V_{DD} = 18V, V_{IN} = 5V, T_A = +125°C, see Figure 4-1, Figure 4-2
Power Supply						
Supply Voltage	V_{DD}	4.5	—	18	V	
Power Supply Current	I_{DD}	—	—	1100	µA	$V_{INA/B}$ = 3V, $V_{ENA/B}$ = 3V
	I_{DD}	—	—	1100	µA	$V_{INA/B}$ = 0V, $V_{ENA/B}$ = 3V
	I_{DD}	—	—	1100	µA	$V_{INA/B}$ = 3V, $V_{ENA/B}$ = 0V
	I_{DD}	—	—	1100	µA	$V_{INA/B}$ = 0V, $V_{ENA/B}$ = 0V

Note 1: Tested during characterization, not production tested.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with 4.5V ≤ V_{DD} ≤ 18V

Parameters	Sym.	Min.	Typ.	Max.	Units	Comments
Temperature Ranges						
Specified Temperature Range	T_A	–40	—	+125	°C	
Maximum Junction Temperature	T_J	—	—	+150	°C	
Storage Temperature Range	T_A	–65	—	+150	°C	
Package Thermal Resistances						
Junction-to-Ambient Thermal Resistance, 8LD MSOP	θ_{JA}	—	158	—	°C/W	Note 1
Junction-to-Ambient Thermal Resistance, 8LD SOIC	θ_{JA}	—	100	—	°C/W	Note 1
Junction-to-Ambient Thermal Resistance, 8LD TDFN	θ_{JA}	—	54	—	°C/W	Note 1
Junction-to-Top Characterization Parameter, 8LD MSOP	Ψ_{JT}	—	2.4	—	°C/W	Note 1
Junction-to-Top Characterization Parameter, 8LD SOIC	Ψ_{JT}	—	5.9	—	°C/W	Note 1
Junction-to-Top Characterization Parameter, 8LD TDFN	Ψ_{JT}	—	0.5	—	°C/W	Note 1
Junction-to-Board Characterization Parameter, 8LD MSOP	Ψ_{JB}	—	115	—	°C/W	Note 1
Junction-to-Board Characterization Parameter, 8LD SOIC	Ψ_{JB}	—	65	—	°C/W	Note 1
Junction-to-Board Characterization Parameter, 8LD TDFN	Ψ_{JB}	—	24	—	°C/W	Note 1

Note 1: Parameter is determined using High K 2S2P 4-Layer board as described in JESD 51-7, as well as JESD 51-5 for packages with exposed pads.

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2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, T_A = +25°C with 4.5V ≤ V_{DD} ≤ 18V.

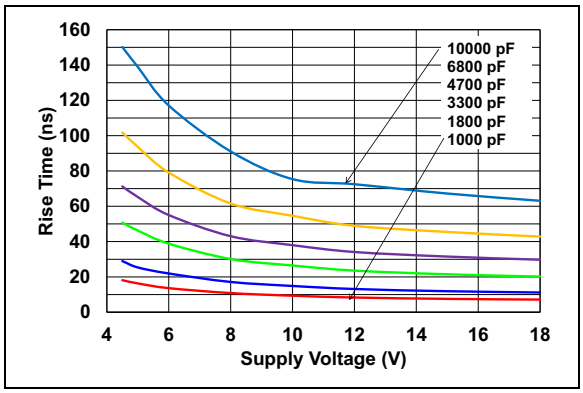

FIGURE 2-1: *Rise Time vs. Supply Voltage.*

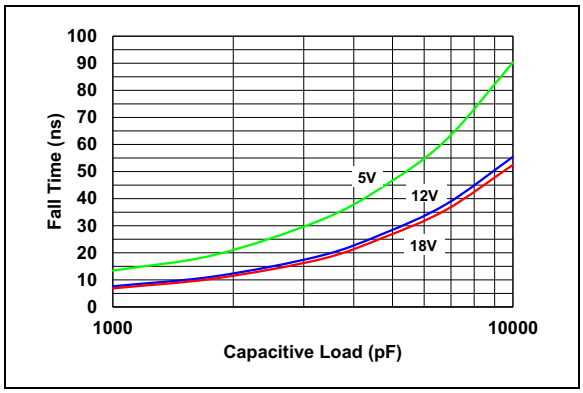

FIGURE 2-4: *Fall Time vs. Capacitive Load.*

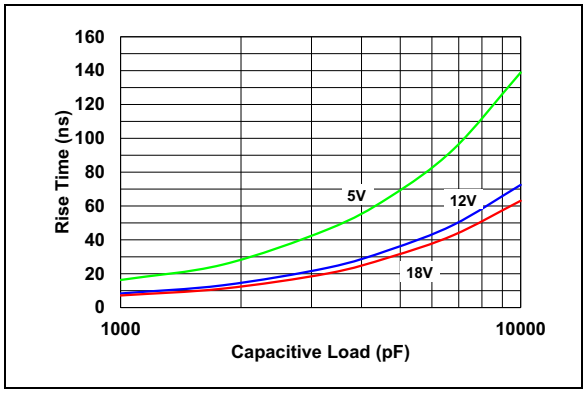

FIGURE 2-2: *Rise Time vs. Capacitive Load.*

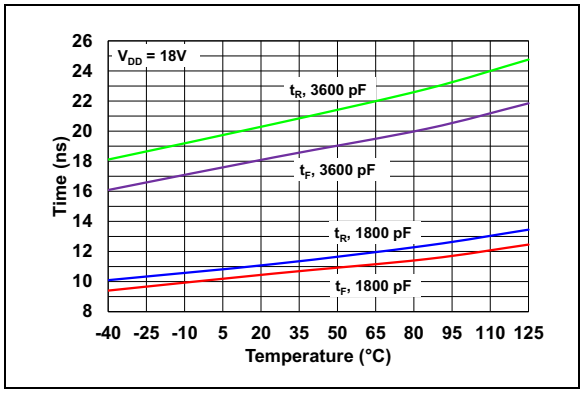

FIGURE 2-5: *Rise and Fall Time vs. Temperature.*

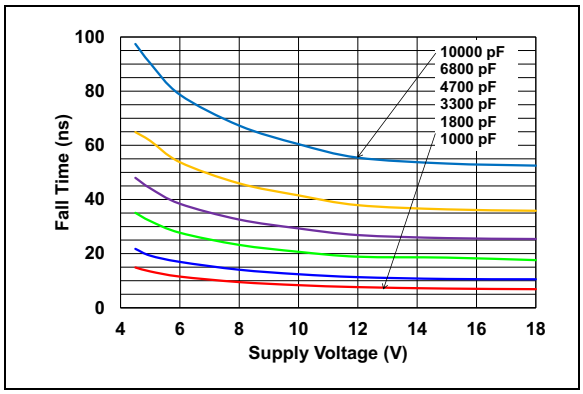

FIGURE 2-3: *Fall Time vs. Supply Voltage.*

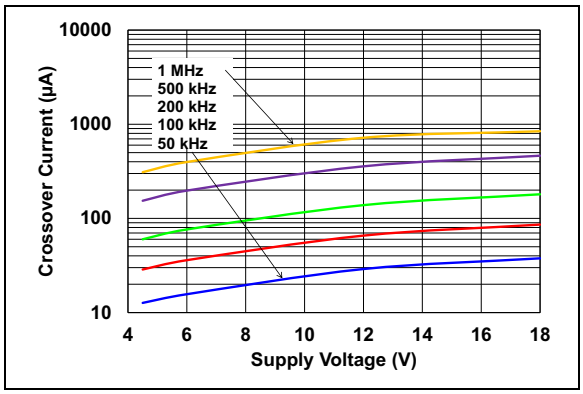

FIGURE 2-6: *Crossover Current vs. Supply Voltage.*

Note: Unless otherwise indicated, T_A = +25°C with 4.5V ≤ V_{DD} ≤ 18V.

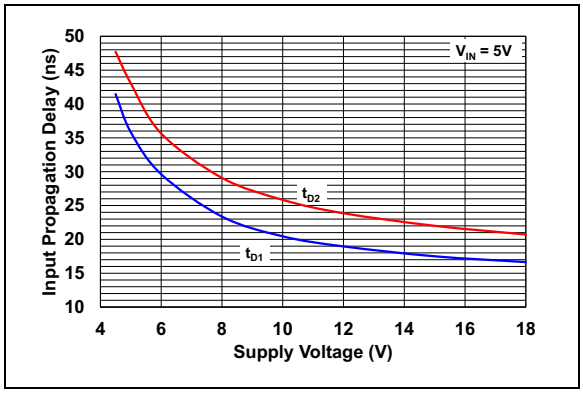

FIGURE 2-7: *Input Propagation Delay vs. Supply Voltage.*

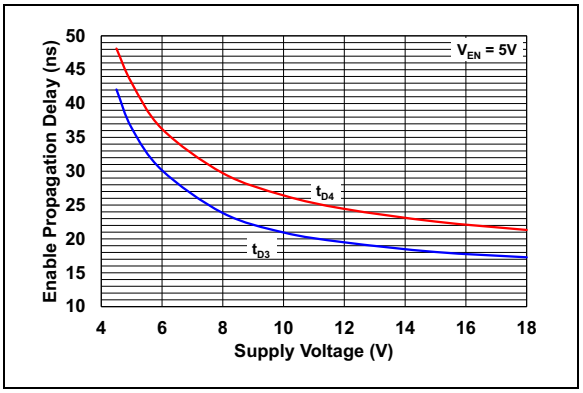

FIGURE 2-10: *Enable Propagation Delay vs. Supply Voltage.*

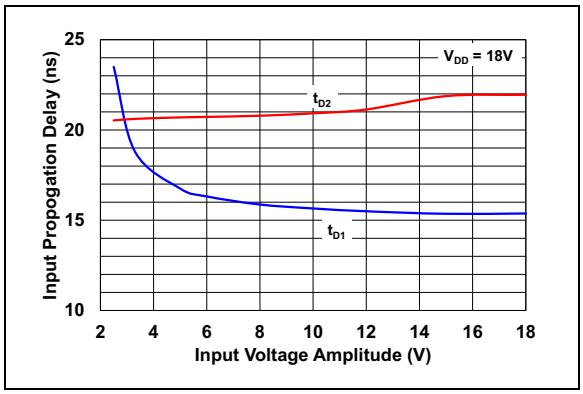

FIGURE 2-8: *Input Propagation Delay Time vs. Input Amplitude.*

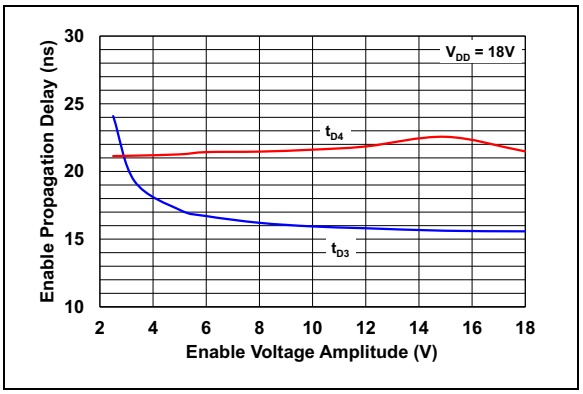

FIGURE 2-11: *Enable Propagation Delay Time vs. Enable Voltage Amplitude.*

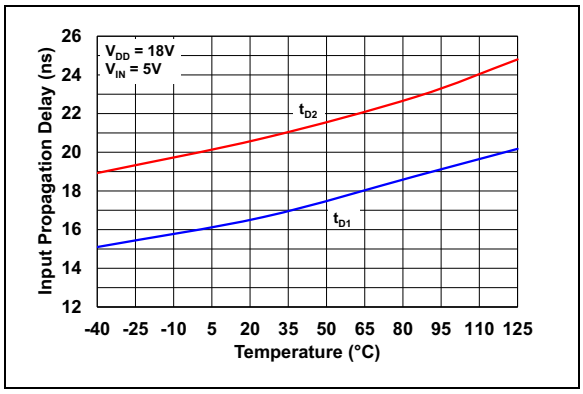

FIGURE 2-9: *Input Propagation Delay vs. Temperature.*

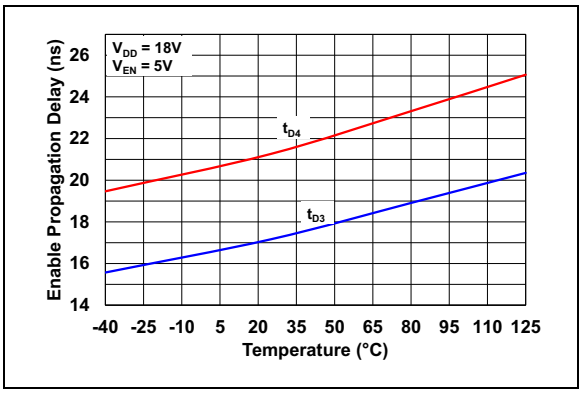

FIGURE 2-12: *Enable Propagation Delay vs. Temperature.*

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Note: Unless otherwise indicated, T_A = +25°C with 4.5V ≤ V_{DD} ≤ 18V.

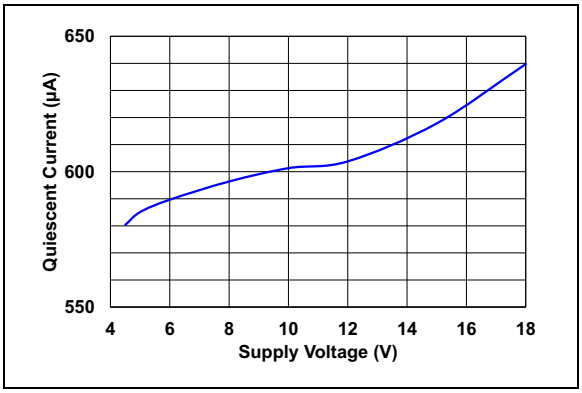

FIGURE 2-13: *Quiescent Supply Current vs. Supply Voltage.*

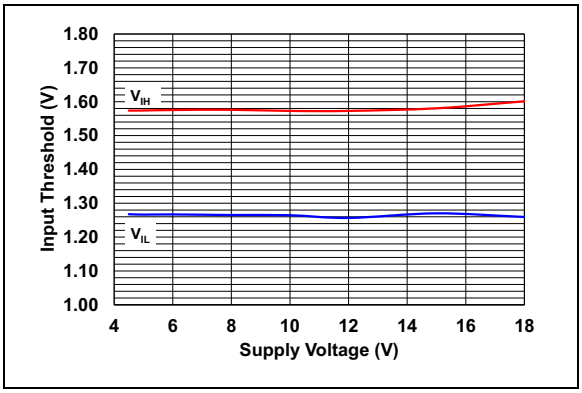

FIGURE 2-16: *Input Threshold vs. Supply Voltage.*

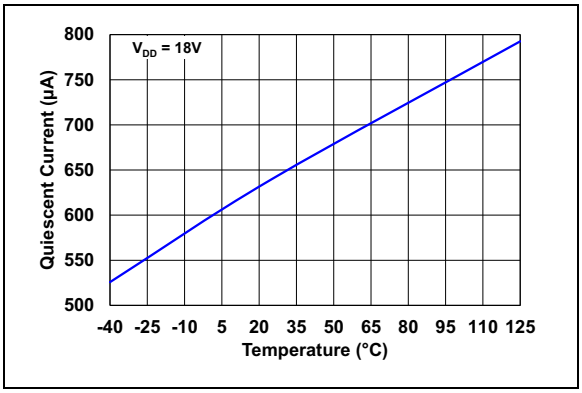

FIGURE 2-14: *Quiescent Supply Current vs. Temperature.*

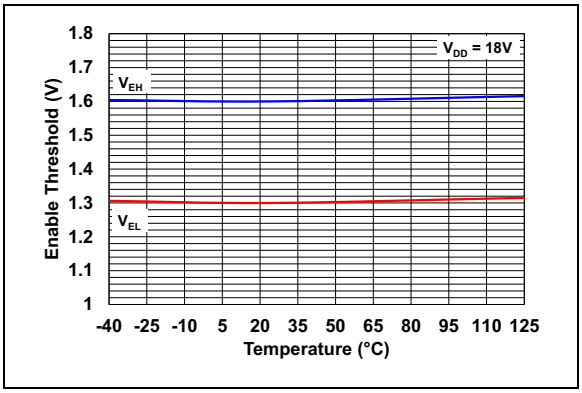

FIGURE 2-17: *Enable Threshold vs. Temperature.*

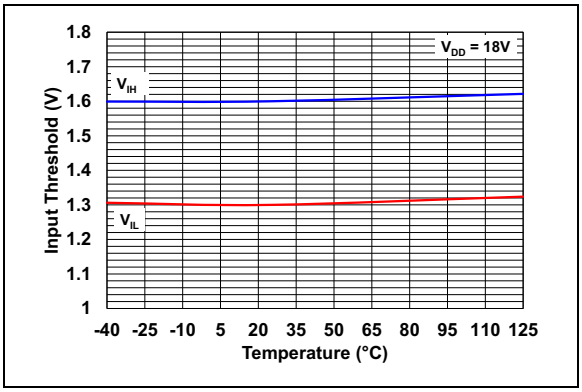

FIGURE 2-15: *Input Threshold vs. Temperature.*

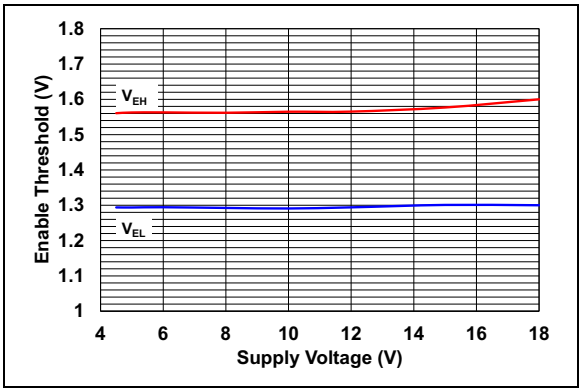

FIGURE 2-18: *Enable Threshold vs. Supply Voltage.*

Note: Unless otherwise indicated, T_A = +25°C with 4.5V ≤ V_{DD} ≤ 18V.

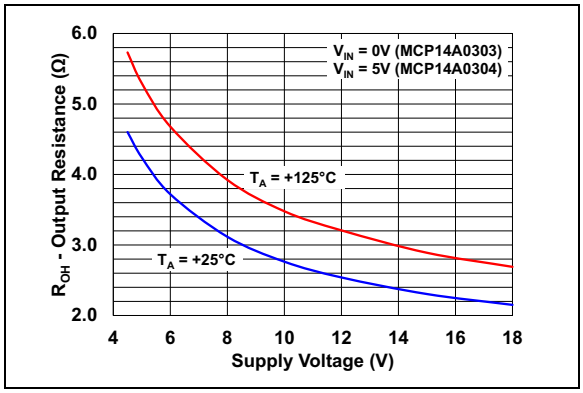

FIGURE 2-19: *Output Resistance (Output High) vs. Supply Voltage.*

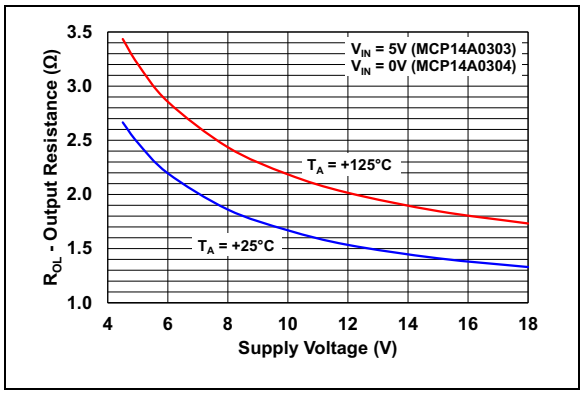

FIGURE 2-20: *Output Resistance (Output Low) vs. Supply Voltage.*

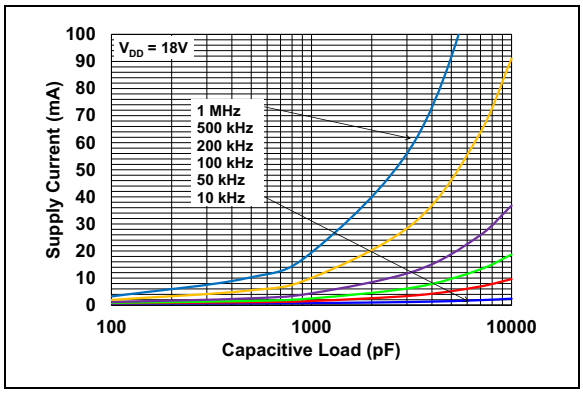

FIGURE 2-21: *Supply Current vs. Capacitive Load (V_{DD} = 18V).*

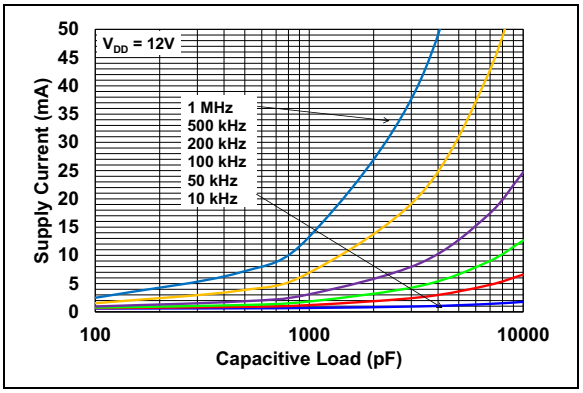

FIGURE 2-22: *Supply Current vs. Capacitive Load (V_{DD} = 12V).*

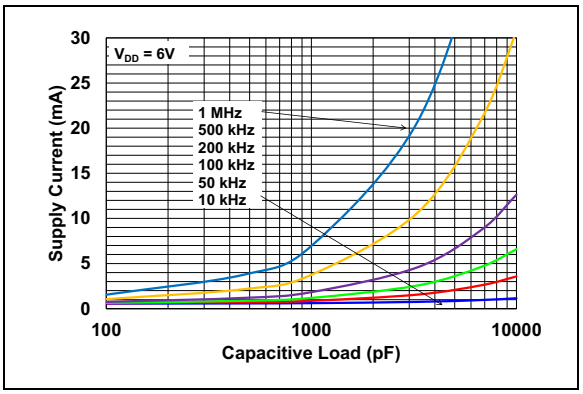

FIGURE 2-23: *Supply Current vs. Capacitive Load (V_{DD} = 6V).*

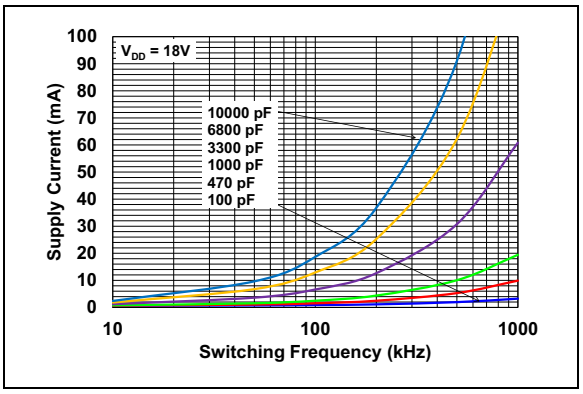

FIGURE 2-24: *Supply Current vs. Frequency (V_{DD} = 18V).*

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Note: Unless otherwise indicated, T_A = +25°C with 4.5V ≤ V_{DD} ≤ 18V.

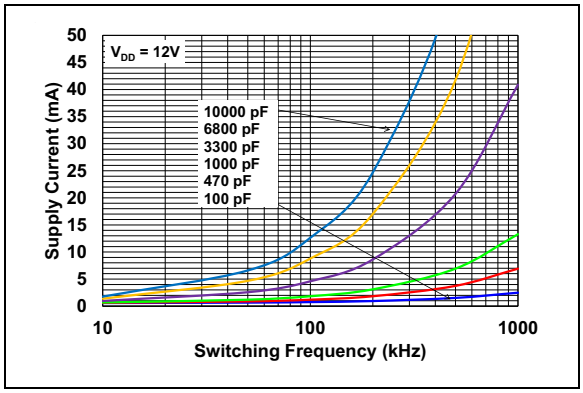

FIGURE 2-25: *Supply Current vs. Frequency (V_{DD} = 12V).*

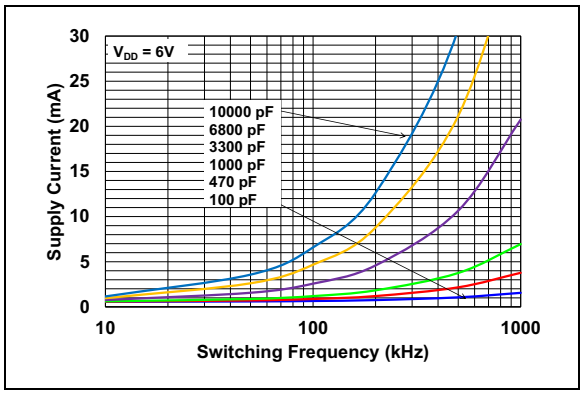

FIGURE 2-26: *Supply Current vs. Frequency (V_{DD} = 6V).*

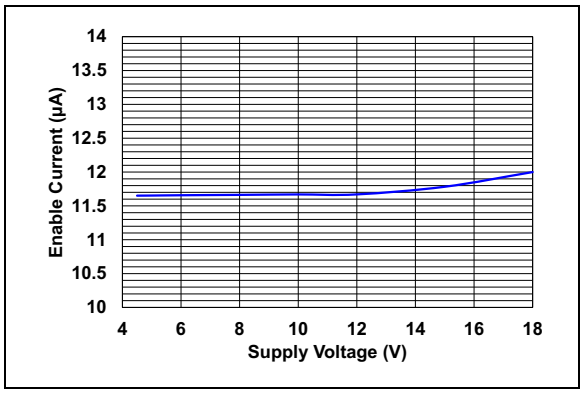

FIGURE 2-27: *Enable Current vs. Supply Voltage.*

NOTES:

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3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

MCP14A0303/4/5		Symbol	Description
8L 2 x 3 TDFN	8L MSOP/SOIC		
1	1	ENA	Enable for Driver A
2	2	INA	Input for Driver A
3	3	GND	Device Ground
4	4	INB	Input for Driver B
5	5	$\overline{OUT}$B/OUTB/OUTB	Push-Pull for Output B
6	6	V_{DD}	Supply Input Voltage
7	7	$\overline{OUT}$A/OUTA/$\overline{OUT}$A	Push-Pull for Output A
8	8	ENB	Enable for Driver B
EP	—	EP	Exposed Thermal Pad (GND)

3.1 Output Pins ($\overline{OUT}$A/OUTA/$\overline{OUT}$A, $\overline{OUT}$B/OUTB/OUTB)

The outputs are CMOS push-pull circuits that are capable of sourcing and sinking 3A of peak current (V_{DD} = 18V). The low output impedance ensures the gate of the external MOSFET stays in the intended state, even during large transients. This output also has a reverse current latch-up rating of 500 mA.

3.2 Device Ground Pin (GND)

GND is the device return pin for the input and output stages. The GND pin should have a low-impedance connection to the bias supply source return. When the capacitive load is discharged, high-peak currents flow through the ground pin.

3.3 Device Enable Pins (ENA, ENB)

The MOSFET driver device enable pins are high-impedance inputs featuring low threshold levels. The enable inputs also have hysteresis between the high and low input levels, allowing them to be driven from slow rising and falling signals, and to provide noise immunity. Driving the enable pins below the threshold disables the corresponding output of the device, pulling $\overline{OUT}$/OUT low, regardless of the status of the input pin. Driving the enable pins above the threshold allows normal operation of the $\overline{OUT}$/OUT pin based on the status of the input pin. The enable pins utilize internal pull-up resistors, allowing the pins to be left floating for standard driver operation.

3.4 Control Input Pins (INA, INB)

The MOSFET driver control inputs are high-impedance inputs featuring low threshold levels. The inputs also have hysteresis between the high and low input levels, allowing them to be driven from slow rising and falling signals, and to provide noise immunity.

3.5 Supply Input Pin (V_{DD})

V_{DD} is the bias supply input for the MOSFET driver and has a voltage range of 4.5V to 18V. This input must be decoupled to ground with a local capacitor. This bypass capacitor provides a localized low-impedance path for the peak currents that are provided to the load.

3.6 Exposed Metal Pad Pin (EP)

The exposed metal pad of the TDFN package is internally connected to GND. Therefore, this pad should be connected to a ground plane to aid in heat removal from the package.

NOTES:

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4.0 APPLICATION INFORMATION

4.1 General Information

MOSFET drivers are high-speed, high-current devices that are intended to source/sink high-peak currents to charge/discharge the gate capacitance of external MOSFETs or Insulated-Gate Bipolar Transistors (IGBTs). In high-frequency switching power supplies, the Pulse-Width Modulation (PWM) controller may not have the drive capability to directly drive the power MOSFET. A MOSFET driver such as the MCP14A0303/4/5 family can be used to provide additional source/sink current capability.

4.2 MOSFET Driver Timing

The ability of a MOSFET driver to transition from a fully-off state to a fully-on state is characterized by the driver's rise time (t_R), fall time (t_F) and propagation delays (t_{D1} and t_{D2}). Figure 4-1 and Figure 4-2 show the test circuit and timing waveform used to verify the MCP14A0303/4/5 timing.

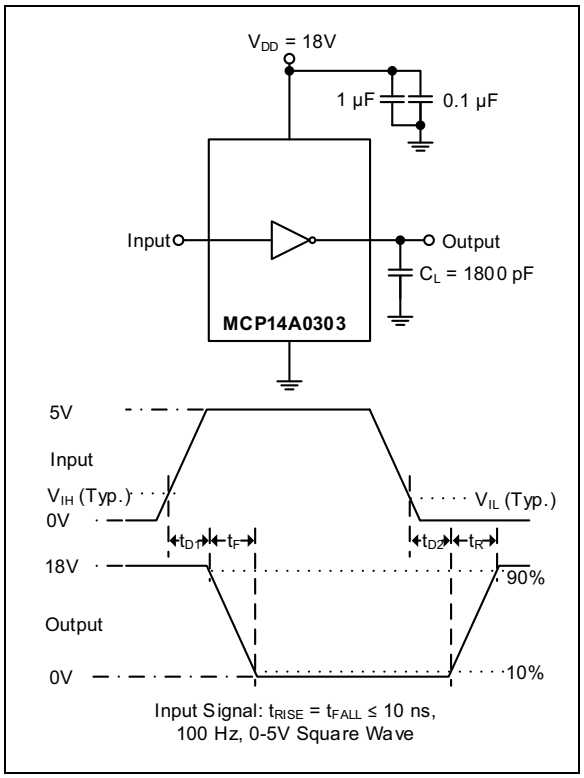

FIGURE 4-1: *Inverting Driver Timing Waveform.*

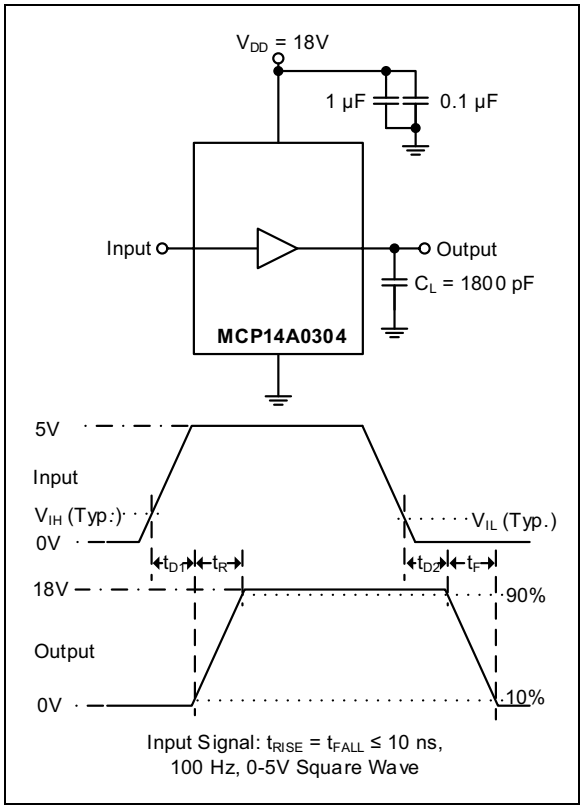

FIGURE 4-2: *Noninverting Driver Timing Waveform.*

4.3 Enable Function

The enable pins (ENA, ENB) provide additional control of the output pins (OUT). These pins are active-high and are internally pulled up to V_{DD} so that the pins can be left floating to provide standard MOSFET driver operation.

When the enable pin input voltages are above the enable pin high-voltage threshold (V_{EN_H}), the corresponding output is enabled and allowed to react to the status of the input pin. However, when the voltage applied to the enable pins falls below the low threshold voltage (V_{EN_L}), the driver's corresponding output is disabled and does not respond to changes in the status of the input pins. When the driver is disabled, the output is pulled down to a low state. Refer to Table 4-1 for the enable pin logic. The threshold voltage levels for the enable pin are similar to the threshold voltage levels of the input pin and are TTL compatible. Hysteresis is provided to help increase the noise immunity of the enable function, avoiding false triggers of the enable signal during driver switching.

There are propagation delays associated with the driver receiving an enable signal and the output reacting. These propagation delays, t_{D3} and t_{D4}, are graphically represented in Figure 4-3.

TABLE 4-1: ENABLE PIN LOGIC

EN	IN	$\overline{OUT}$	OUT
H	H	L	H
H	L	H	L
L	X	L	L

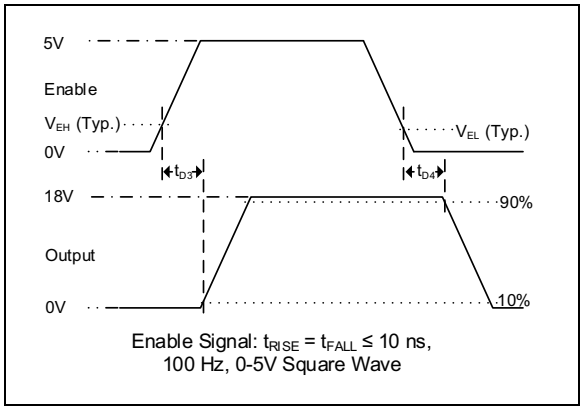

FIGURE 4-3: *Enable Timing Waveform.*

4.4 Decoupling Capacitors

Careful Printed Circuit Board (PCB) layout and decoupling capacitors are required when using power MOSFET drivers. Large current is required to charge and discharge capacitive loads quickly. For example, approximately 720 mA are needed to charge a 1000 pF load with 18V in 25 ns.

To operate the MOSFET driver over a wide frequency range with low supply impedance, it is recommended to place 1.0 µF and 0.1 µF low ESR ceramic capacitors in parallel between the driver V_{DD} and GND. These capacitors should be placed close to the driver to minimize circuit board parasitics and provide a local source for the required current.

4.5 PCB Layout Considerations

Proper PCB layout is important in high-current, fast-switching circuits to provide proper device operation and robustness of design. Improper component placement may cause errant switching, excessive voltage ringing or circuit latch-up. The PCB trace loop length and inductance should be minimized by the use of ground planes or traces under the MOSFET gate drive signal. Separate analog and power grounds and local driver decoupling should also be used.

Placing a ground plane beneath the MCP14A0303/4/5 devices will help as a radiated noise shield, as well as providing some heat sinking for power dissipated within the device.

4.6 Power Dissipation

The total internal power dissipation in a MOSFET driver is the summation of three separate power dissipation elements, as shown in Equation 4-1.

EQUATION 4-1:

$$P_T = P_L + P_Q + P_{CC}$$

Where:

P_T = Total power dissipation
P_L = Load power dissipation
P_Q = Quiescent power dissipation
P_{CC} = Operating power dissipation

4.6.1 CAPACITIVE LOAD DISSIPATION

The power dissipation caused by a capacitive load is a direct function of the frequency, total capacitive load and supply voltage. The power lost in the MOSFET driver for a complete charging and discharging cycle of a MOSFET is shown in Equation 4-2.

EQUATION 4-2:

$$P_L = f \times C_T \times V_{DD}^2$$

Where:

f = Switching frequency
C_T = Total load capacitance
V_{DD} = MOSFET driver supply voltage

4.6.2 QUIESCENT POWER DISSIPATION

The power dissipation associated with the quiescent current draw depends on the state of the Input and Enable pins. See **Section 1.0 "Electrical Characteristics"** for typical quiescent current draw values in different operating states. The quiescent power dissipation is shown in Equation 4-3.

EQUATION 4-3:

$$P_Q = (I_{QH} \times D + I_{QL} \times (1 - D)) \times V_{DD}$$

Where:

I_{QH} = Quiescent current in the High state
D = Duty cycle
I_{QL} = Quiescent current in the Low state
V_{DD} = MOSFET driver supply voltage

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4.6.3 OPERATING POWER DISSIPATION

The operating power dissipation occurs each time the MOSFET driver output transitions because, for a very short period of time, both MOSFETs in the output stage are on simultaneously. This cross-conduction current leads to a power dissipation described in Equation 4-4.

EQUATION 4-4:

$$P_{CC} = V_{DD} \times I_{CO}$$

Where:

I_{CO} = Crossover current

V_{DD} = MOSFET driver supply voltage

NOTES:

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5.0 PACKAGING INFORMATION

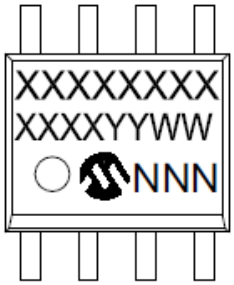
5.1 Package Marking Information

8-Lead MSOP

Part Number	Code
MCP14A0303-E/MS	A0303
MCP14A0304-E/MS	A0304
MCP14A0305-E/MS	A0305

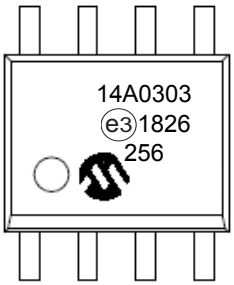
Example:

8-Lead SOIC

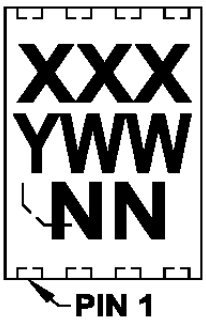


Part Number	Code
MCP14A0303-E/SN	14A0303
MCP14A0304-E/SN	14A0304
MCP14A0305-E/SN	14A0305

Example:

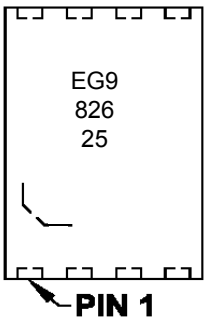


8-Lead TDFN



Part Number	Code
MCP14A0303-E/MNY	EG9
MCP14A0304-E/MNY	EH1
MCP14A0305-E/MNY	EH2

Example:

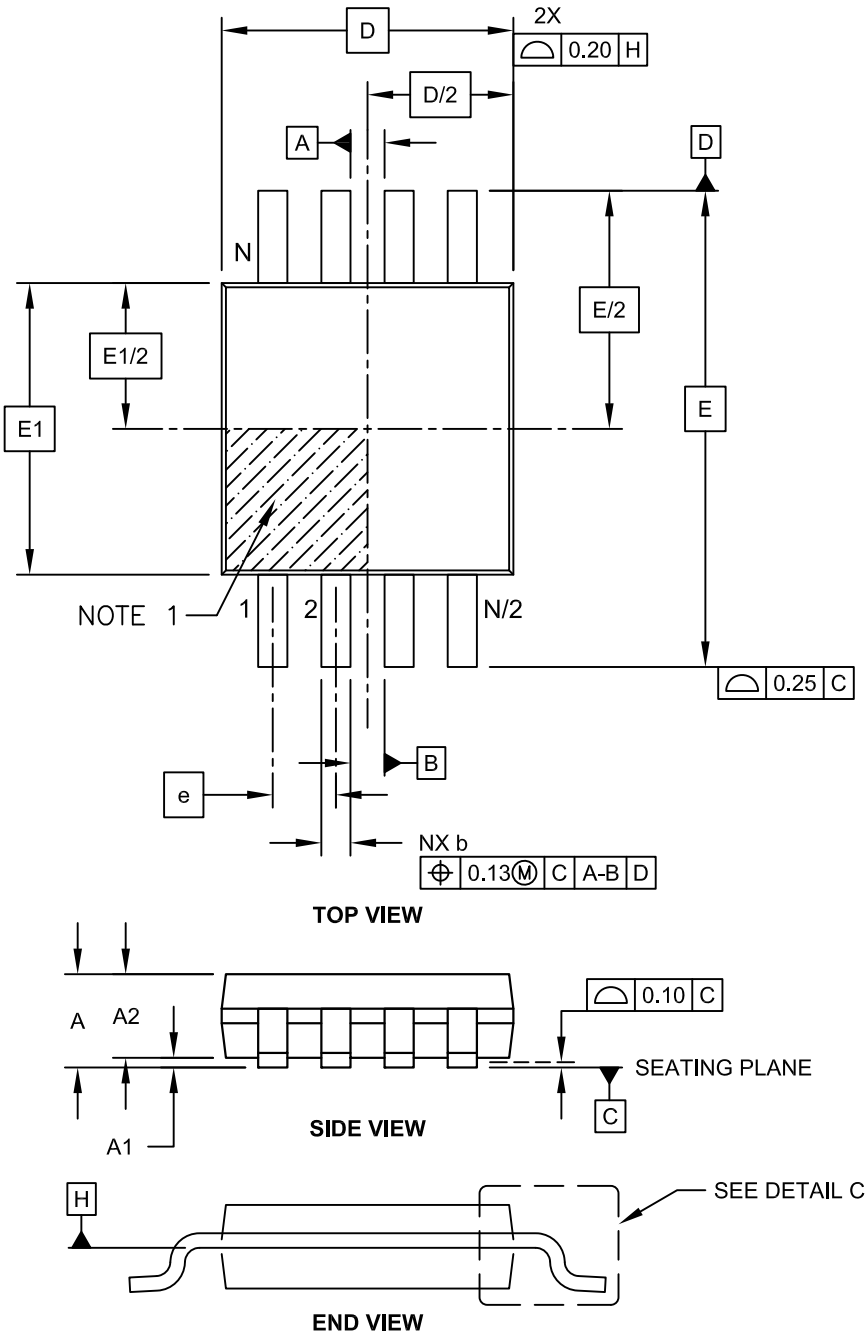


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-111C Sheet 1 of 2

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8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

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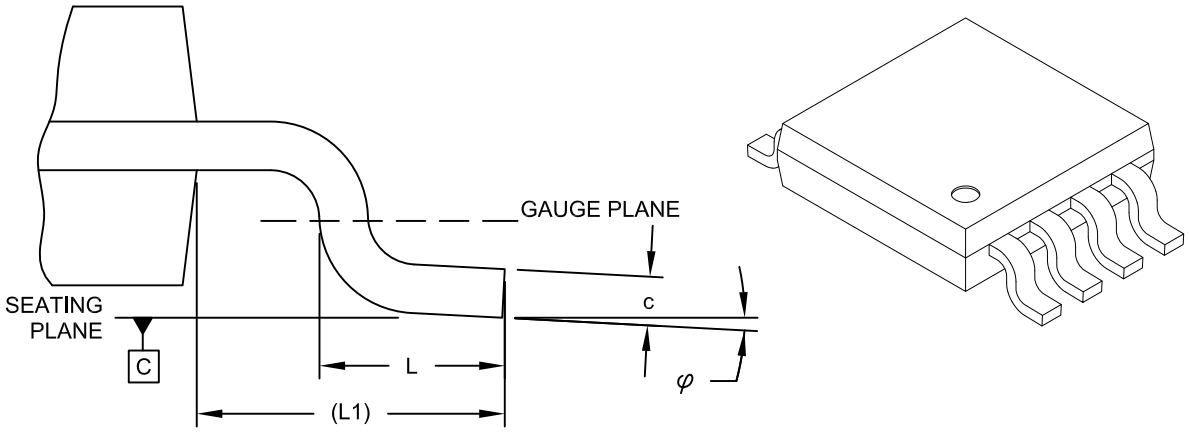

DETAIL C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.65 BSC	
Overall Height	A	-	-	1.10
Molded Package Thickness	A2	0.75	0.85	0.95
Standoff	A1	0.00	-	0.15
Overall Width	E		4.90 BSC	
Molded Package Width	E1		3.00 BSC	
Overall Length	D		3.00 BSC	
Foot Length	L	0.40	0.60	0.80
Footprint	L1		0.95 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.08	-	0.23
Lead Width	b	0.22	-	0.40

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-111C Sheet 2 of 2

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8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

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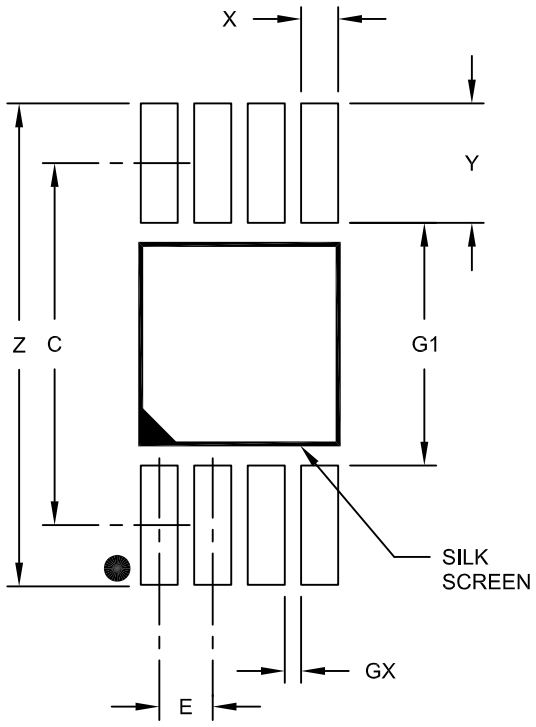

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		4.40	
Overall Width	Z			5.85
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.45
Distance Between Pads	G1	2.95		
Distance Between Pads	GX	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2111A

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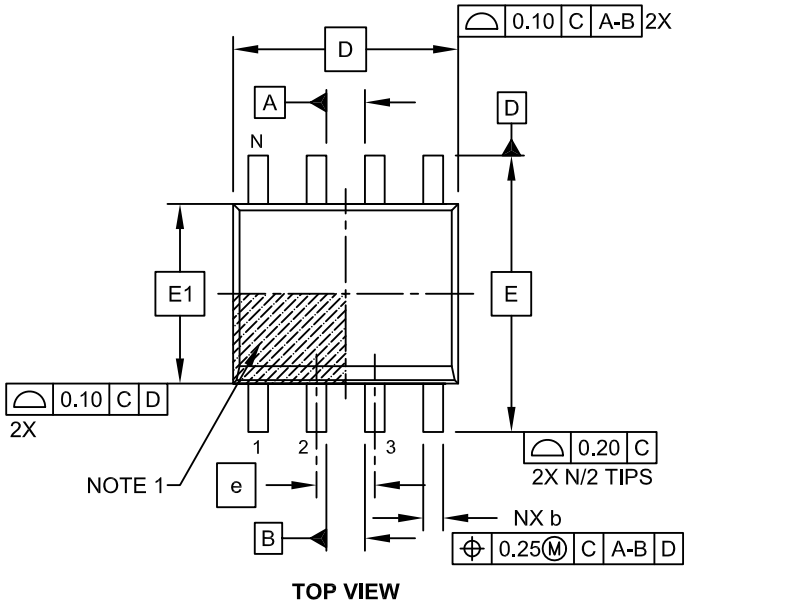
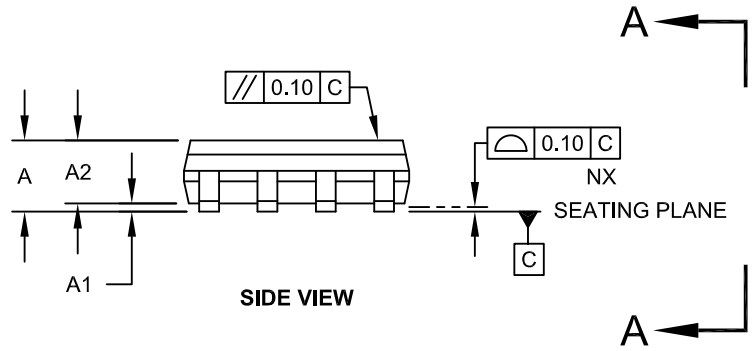
8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

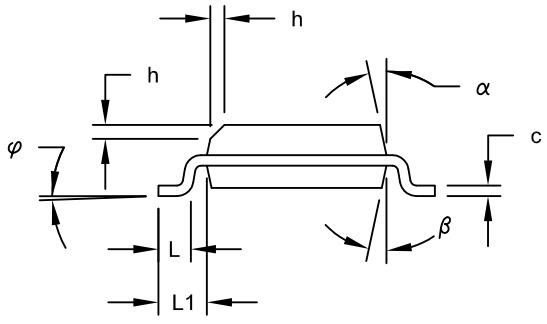
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

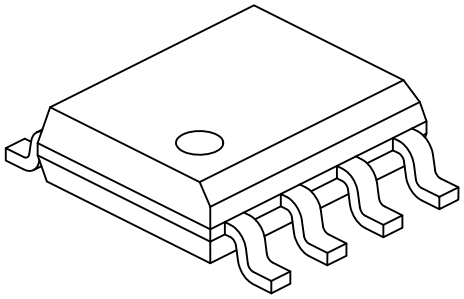


VIEW A-A

Microchip Technology Drawing No. C04-057C Sheet 1 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		4.90 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

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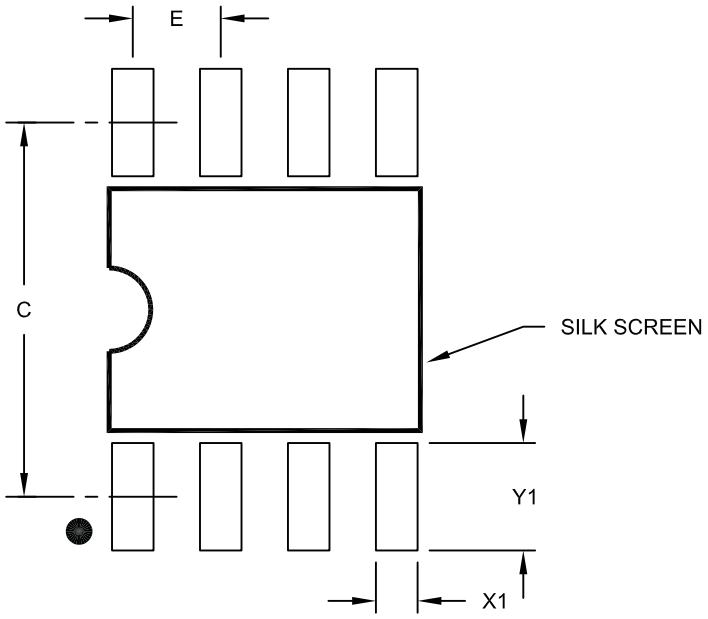


RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

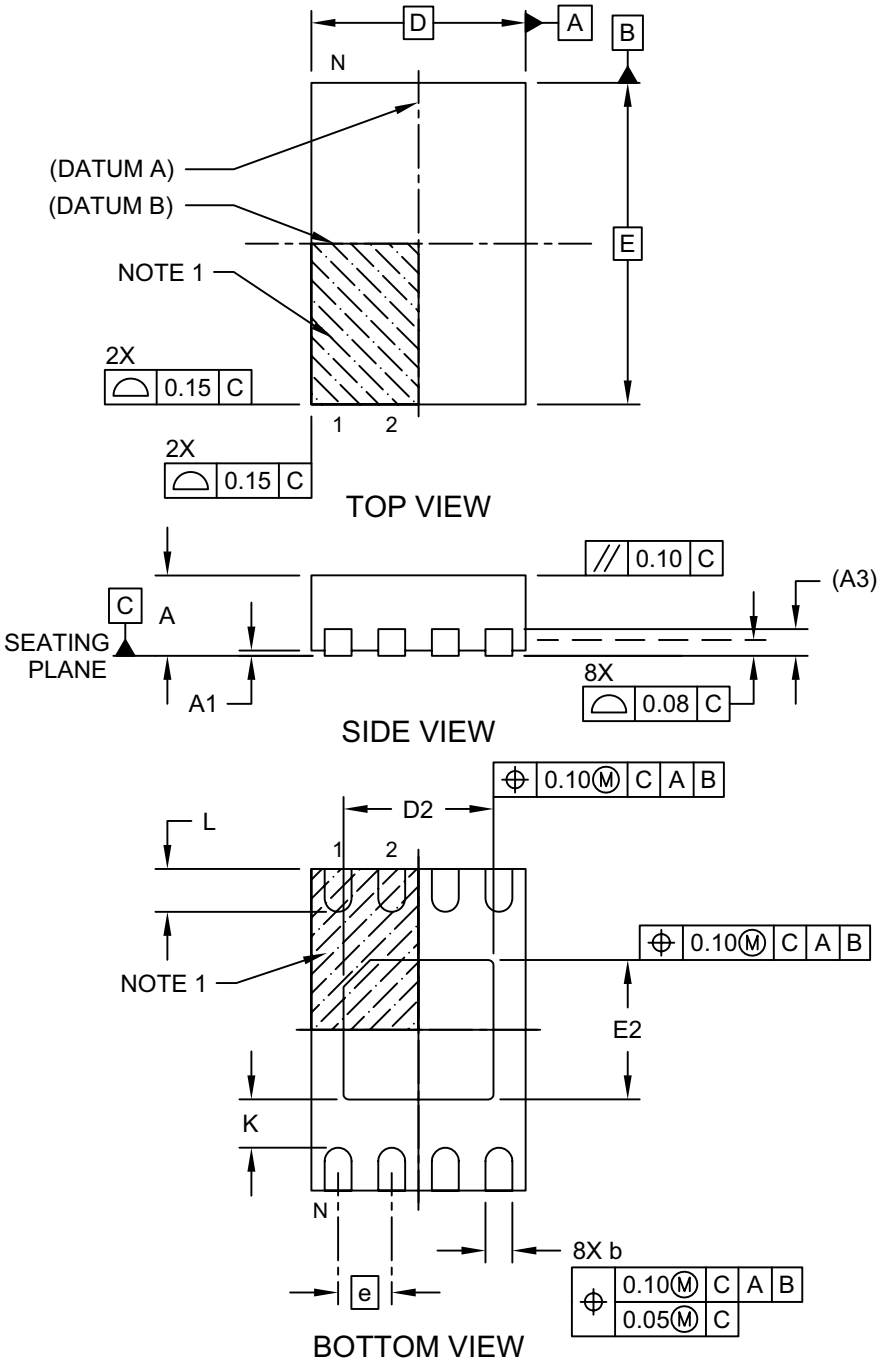
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

8-Lead Plastic Dual Flat, No Lead Package (MNY) – 2x3x0.8 mm Body [TDFN] With 1.4x1.3 mm Exposed Pad (JEDEC Package type WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing No. C04-129-MNY Rev E Sheet 1 of 2

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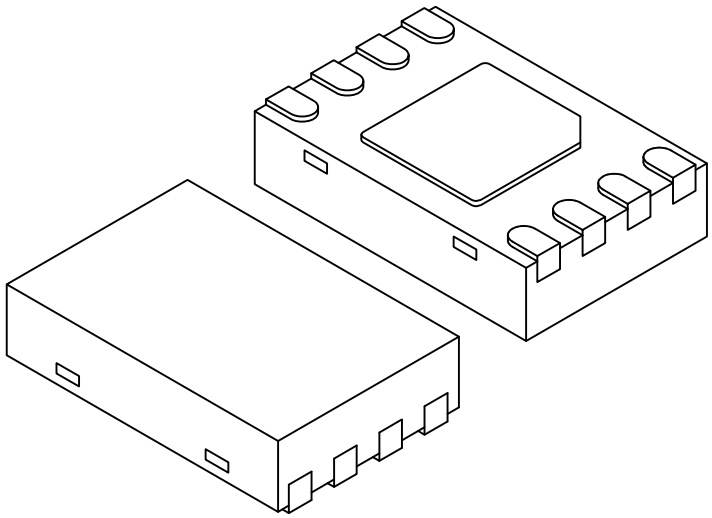
8-Lead Plastic Dual Flat, No Lead Package (MNY) – 2x3x0.8 mm Body [TDFN] With 1.4x1.3 mm Exposed Pad (JEDEC Package type WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.70	0.75	0.80
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Length	D		2.00 BSC	
Overall Width	E		3.00 BSC	
Exposed Pad Length	D2	1.35	1.40	1.45
Exposed Pad Width	E2	1.25	1.30	1.35
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.25	0.30	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated
4. Dimensioning and tolerancing per ASME Y14.5M

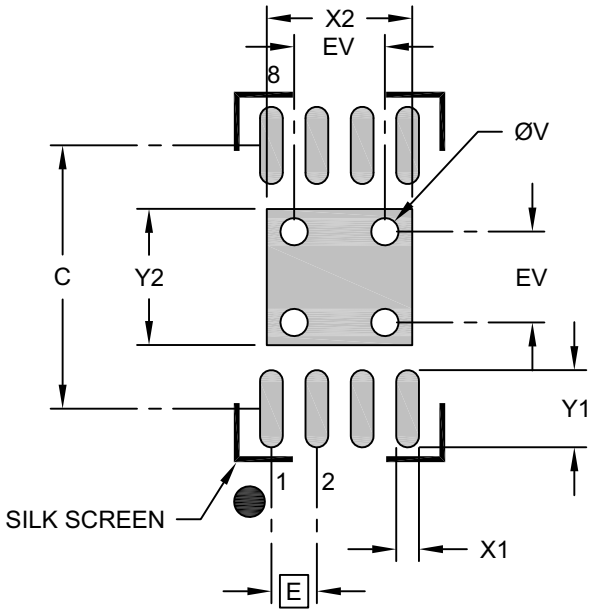
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-129-MNY Rev E Sheet 2 of 2

8-Lead Plastic Dual Flat, No Lead Package (MNY) – 2x3x0.8 mm Body [TDFN] With 1.4x1.3 mm Exposed Pad (JEDEC Package type WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			1.60
Optional Center Pad Length	Y2			1.50
Contact Pad Spacing	C		2.90	
Contact Pad Width (X8)	X1			0.25
Contact Pad Length (X8)	Y1			0.85
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-129-MNY Rev. B

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APPENDIX A: REVISION HISTORY

Revision A (June 2018)

- Original Release of this Document.

NOTES:

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	–X	/XX
Device	Tape and Reel	Temperature Range	Package

Device:	MCP14A0303: High-Speed MOSFET Driver MCP14A0303T: High-Speed MOSFET Driver (Tape and Reel) MCP14A0304: High-Speed MOSFET Driver MCP14A0304T: High-Speed MOSFET Driver (Tape and Reel) MCP14A0305: High-Speed MOSFET Driver MCP14A0305T: High-Speed MOSFET Driver (Tape and Reel)
Temperature Range:	E = -40°C to +125°C (Extended)
Package:	MS = Plastic Micro Small Outline Package (MSOP), 8-lead SN = Plastic Small Outline Package (SOIC), 8-lead MNY = Plastic Dual Flat, No Lead Package (TDFN), 8-lead

Examples:

a) MCP14A0303T-E/MS: Tape and Reel, Extended temperature, 8LD MSOP package

b) MCP14A0304T-E/SN: Tape and Reel, Extended temperature, 8LD SOIC package

c) MCP14A0305T-E/MNY: Tape and Reel Extended temperature, 8LD TDFN package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

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